

DSC160N120W

18 Amps, 1200 Volts N-Channel Sic Power MOSFET

Features

- 18A,1200V, $R_{DS(ON)MAX}=196m\Omega$ @ $V_{GS}=20V/10A$
- High Blocking Voltage with low On-Resistance
- High Speed Switching with Low Capacitance
- Easy to Parallel and Simple to Drive

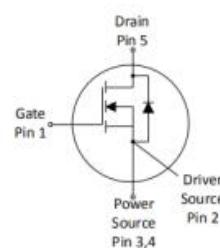
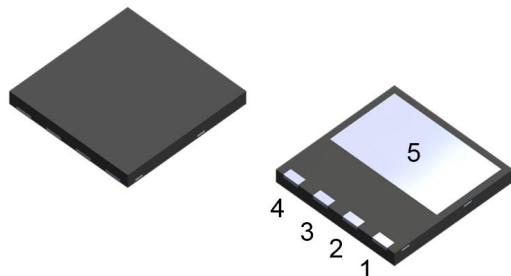
Benefits

- Higher System Efficiency
- Reduced Cooling Requirements
- Increased Power Density
- Increased System Switching Frequency

Applications

- Solar Inverters
- High Voltage DC/DC Converters
- Motor Drivers
- Switch Mode Power Supplies
- Pulsed Power applications

DFN8×8



Absolute Maximum Ratings ($T_c=25^\circ C$, unless otherwise noted)

Parameter	Symbol	Value	UNIT	Test Conditions
Drain-Source Voltage	V_{DSmax}	1200	V	$V_{GS}=0V, I_{DS}=100\mu A$
Gate-Source Voltage(dynamic)	V_{GSmax}	-10/+25		Absolute maximum values
Gate-Source Voltage (static)	V_{GSop}	-5/+20		Recommended operational values
Continuous Drain Current	I_D	18	A	$V_{GS}=20V, T_c=25^\circ C$
Pulsed Drain Current	$I_{D(pulse)}$	40	A	Pulse width t_p limited by T_{Jmax}
Power Dissipation	P_D	62.5	W	$T_c=25^\circ C, T_J=150^\circ C$
Operating Junction and Storage Temperature Range	T_J, T_{STG}	-55 to +150	°C	

Thermal Characteristics

Parameter	Symbol	DSC160N120W	Units
Maximum Junction-to-Case	R_{thJC}	2.0	°C/W

Electrical Characteristics ($T_c=25^\circ\text{C}$,unless otherwise noted)							
Parameter	Symbol	Test Conditions		Min	Typ	Max	Units
Off Characteristics							
Drain-Source Breakdown Voltage	BV_{DSS}	$\text{V}_{\text{GS}}=0\text{V}, \text{I}_D=100\mu\text{A}, \text{T}_c=25^\circ\text{C}$		1200	—	—	V
Zero Gate Voltage Drain Current	I_{DSS}	$\text{V}_{\text{DS}}=1200\text{V}, \text{V}_{\text{GS}}=0\text{V}$		—	1	100	μA
Gate-Body Leakage Current,Forward	I_{GSSF}	$\text{V}_{\text{GS}}=25\text{V}, \text{V}_{\text{DS}}=0\text{V}$		—	10	250	nA
Gate-Body Leakage Current,Reverse	I_{GSSR}	$\text{V}_{\text{GS}}=-10\text{V}, \text{V}_{\text{DS}}=0\text{V}$		—	10	250	nA
On Characteristics							
Gate-Source Threshold Voltage	$\text{V}_{\text{GS(th)}}$	$\text{V}_{\text{DS}}=\text{V}_{\text{GS}}, \text{I}_D=2.5\text{mA}$		2.0	2.4	4.0	V
Drain-Source On-State Resistance	$\text{R}_{\text{DS(on)}}$	$\text{V}_{\text{GS}}=20\text{V}, \text{I}_D=10\text{A}$		—	160	196	$\text{m}\Omega$
		$\text{V}_{\text{GS}}=20\text{V}, \text{I}_D=10\text{A}, \text{T}_j=150^\circ\text{C}$		—	280	—	
Dynamic Characteristics							
Input Capacitance	C_{iss}	$\text{V}_{\text{DS}}=1000\text{V}, \text{V}_{\text{GS}}=0\text{V}, \text{f}=1.0\text{MHz}, \text{V}_{\text{AC}}=25\text{mV}$		—	890	—	pF
Output Capacitance	C_{oss}			—	54	—	pF
Reverse Transfer Capacitance	C_{rss}			—	8.5	—	pF
Coss Stored Energy	E_{oss}			—	31	—	μJ
Switching Characteristics							
Turn-On Delay Time	$t_{\text{d(on)}}$	$\text{V}_{\text{DS}}=800\text{V}, \text{V}_{\text{GS}}=-5\text{V}/20\text{V}, \text{I}_D=10\text{A}, \text{R}_g=2.5\Omega, \text{R}_L=80\Omega$		—	8	—	ns
Turn-On Rise Time	t_r			—	9	—	ns
Turn-Off Delay Time	$t_{\text{d(off)}}$			—	14	—	ns
Turn-Off Fall Time	t_f			—	9	—	ns
Turn-On Switching Energy	E_{ON}	$\text{V}_{\text{DS}}=800\text{V}, \text{V}_{\text{GS}}=-5\text{V}/20\text{V}, \text{I}_D=10\text{A}, \text{R}_g=2.5\Omega, \text{L}=200\mu\text{H}$		—	315	—	μJ
Turn-Off Switching Energy	E_{OFF}			—	63	—	μJ
Internal Gate Resistance	R_g		$\text{f}=1\text{MHz}, \text{V}_{\text{AC}}=25\text{mV}$	—	5.5	—	Ω
Total Gate Charge	Q_g	$\text{V}_{\text{DS}}=800\text{V}, \text{I}_D=10\text{A}, \text{V}_{\text{GS}}=-5\text{V}/20\text{V}$		—	49	—	nC
Gate-Source Charge	Q_{gs}			—	17	—	
Gate-Drain Charge	Q_{gd}			—	9	—	
Reverse Diode Characteristics							
Diode Forward Voltage	V_{SD}	$\text{V}_{\text{GS}}=-5\text{V}, \text{I}_{\text{SD}}=5\text{A}$		—	4.2	—	V
Continuous Diode Forward Current	I_s	$\text{T}_c=25^\circ\text{C}$		—	—	23	A
Reverse Recover Time	t_{rr}	$\text{V}_{\text{R}}=800\text{V}, \text{I}_{\text{SD}}=10\text{A}$		—	28	—	ns
Reverse Recovery Charge	Q_{rr}			—	50	—	nc
Peak Reverse Recovery Current	I_{rrm}			—	3	—	A

RATING AND CHARACTERISTIC CURVES

Figure.1 Output Characteristics $T_j=25^\circ\text{C}$

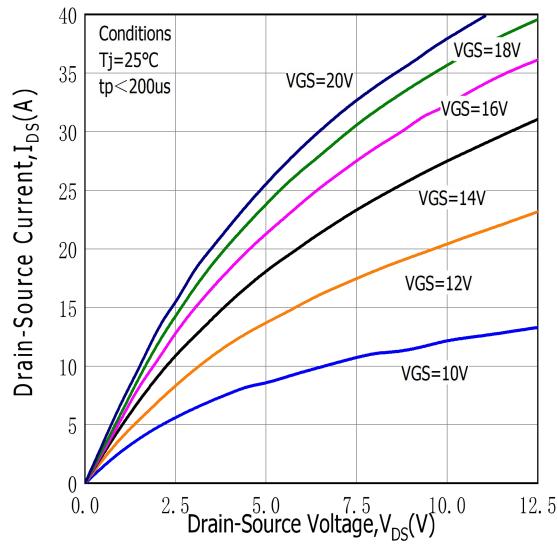


Figure.3 On-Resistance vs.Temperature

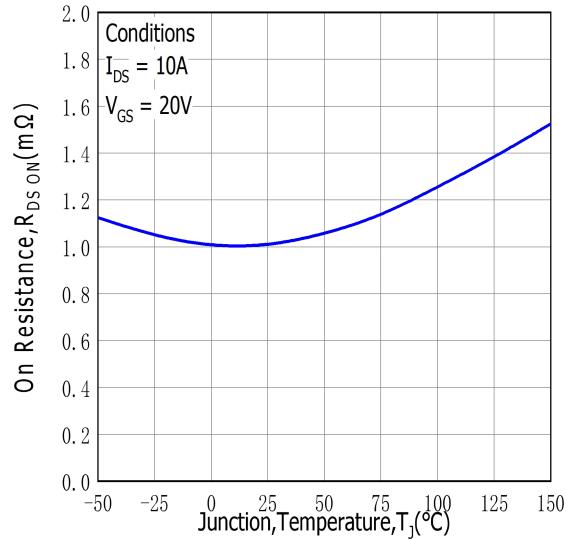


Figure.5 On-Resistance vs.Temperature for Various Gate Voltage

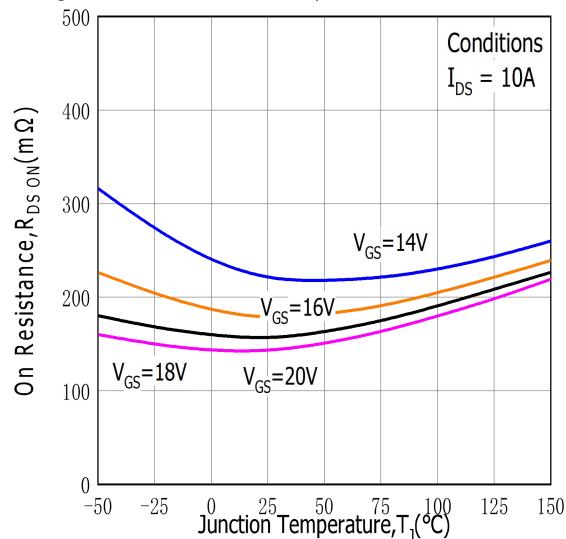


Figure.2 Output Characteristics $T_j=150^\circ\text{C}$

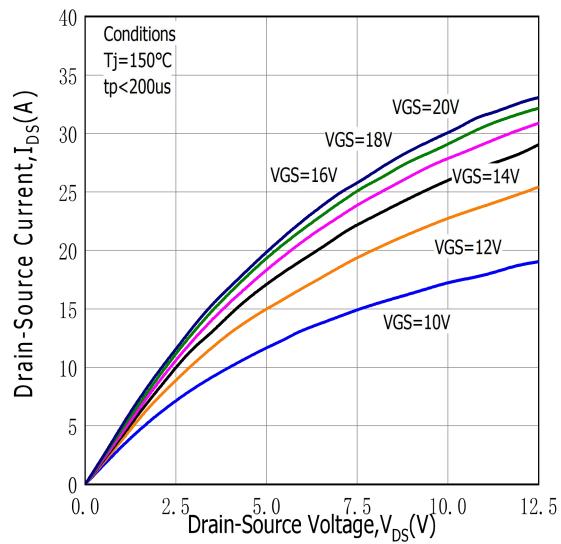


Figure.4 On-Resistance vs.Drain Current for Various Temperatures

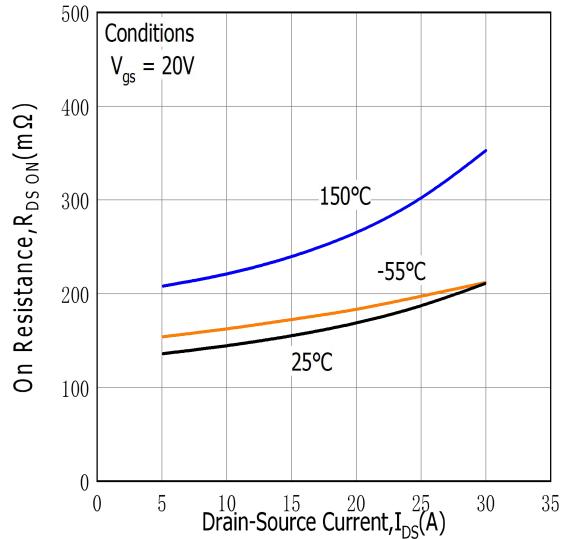


Figure.6 Transfer Characteristic for Various Junction Temperatures

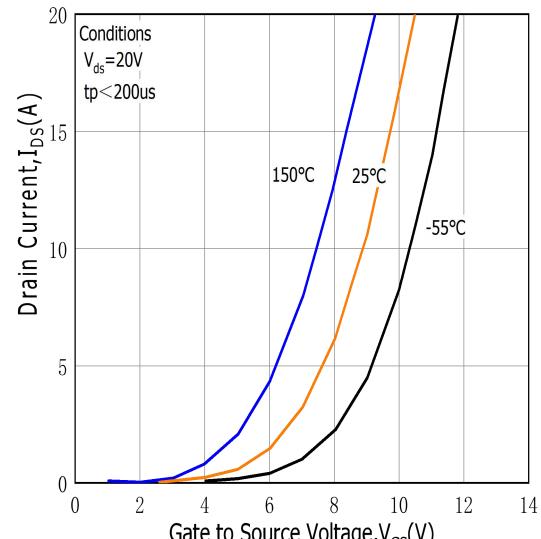


Figure.7 Body Diode Characteristic at 25°C

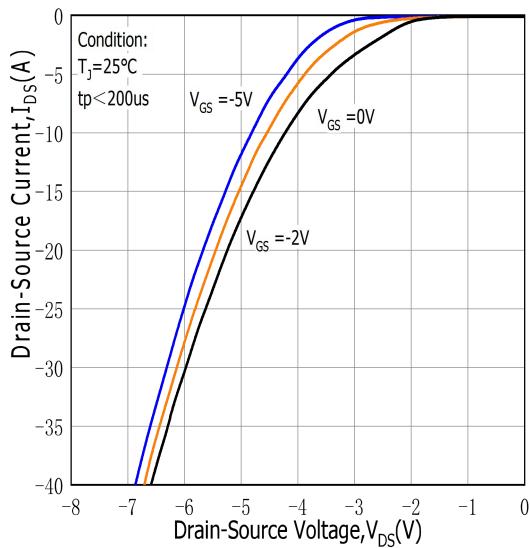


Figure.8 Body Diode Characteristic at 150°C

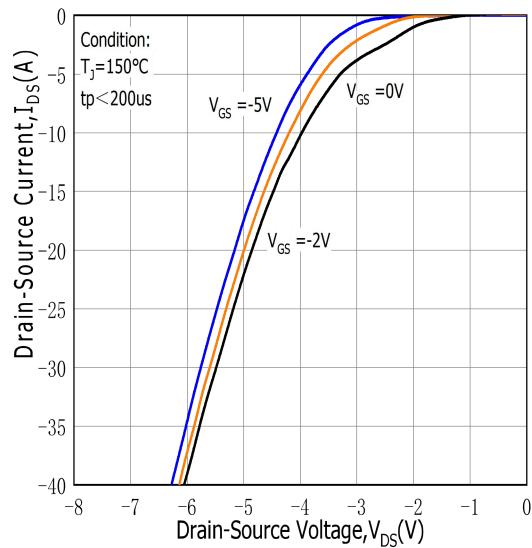


Figure.9 Threshold Voltage vs. Temperature

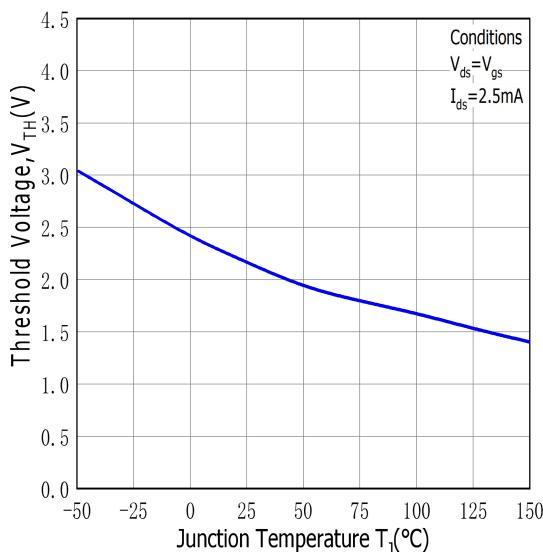


Figure.10 Capacitances vs. Drain-Source Voltage(0-200V)

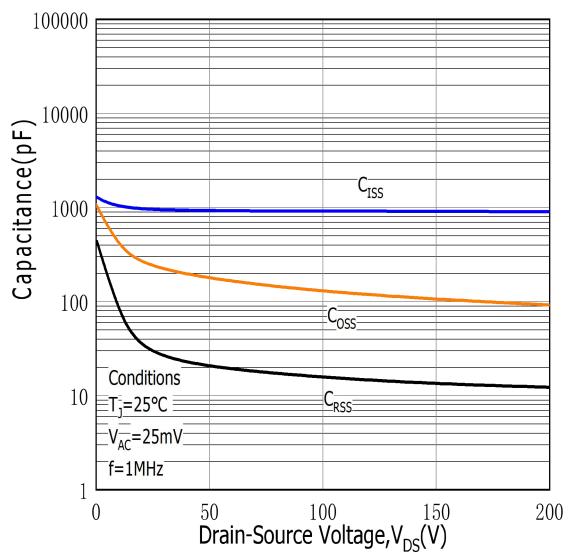
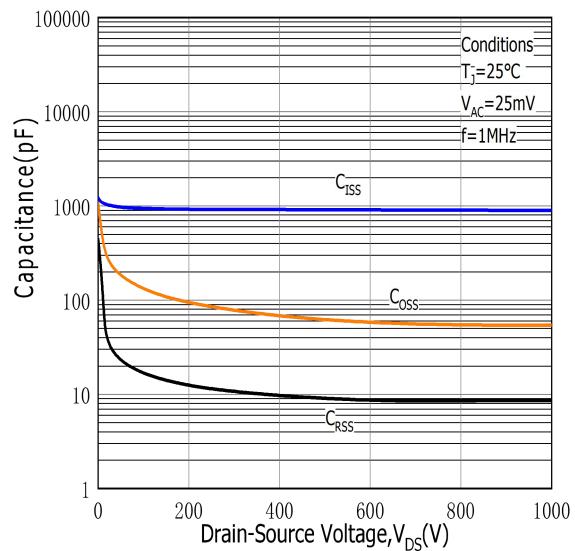
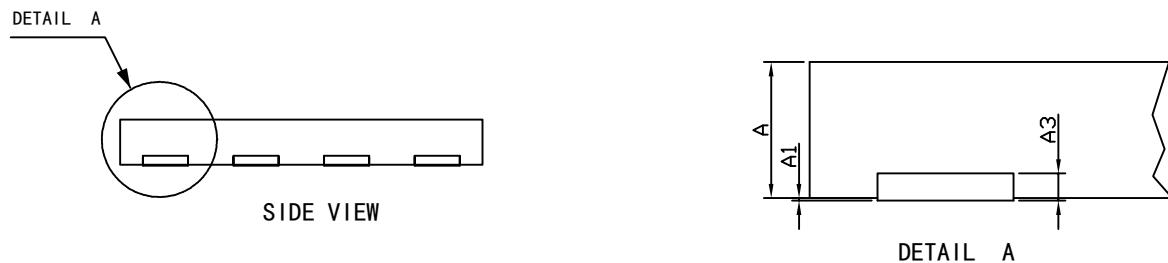
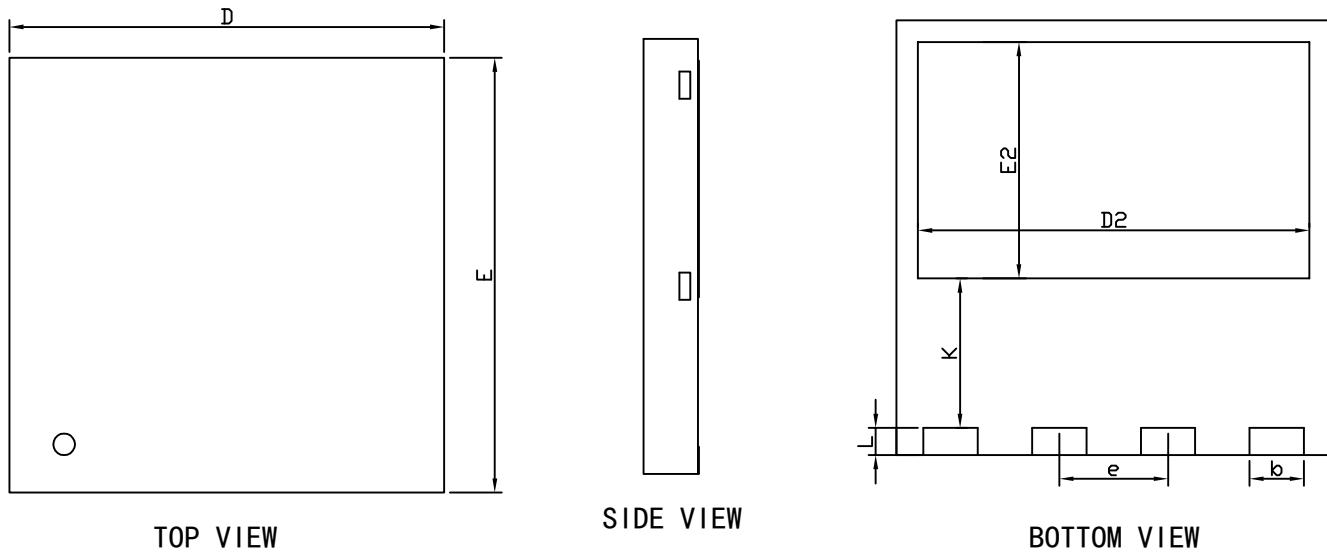


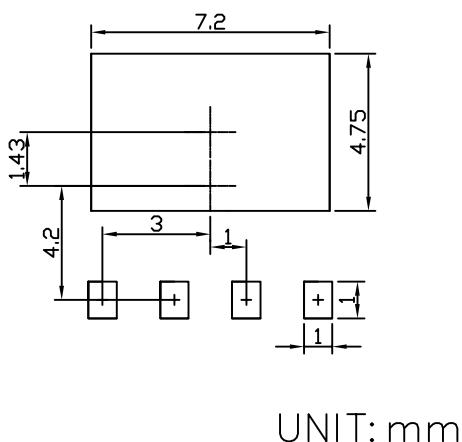
Figure.11 Capacitances vs. Drain-Source Voltage(0-1000V)



DFN8x8 PACKAGE OUTLINE



RECOMMENDED LAND PATTERN



	MIN	NOM	MAX
A	0.90	1.00	1.10
A1	0.00	0.02	0.05
A3		0.20	
b	0.90	1.00	1.10
D	7.90	8.00	8.10
E	7.90	8.00	8.10
D2	7.10	7.20	7.30
E2	4.25	4.35	4.45
e	1.90	2.00	2.10
K	2.65	2.75	2.85
L	0.40	0.50	0.60